SCBS205C - MARCH 1993 - REVISED MAY 1997

● Members of the Texas Instruments <i>Widebus</i> ™ Family	SN54ABT16374A WD PACKAGE SN74ABT16374A DGG OR DL PACKAGE (TOP VIEW)
 State-of-the-Art EPIC-IIB[™] BiCMOS Design Significantly Reduces Power Dissipation 	
 ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015 	1Q1 [2 47] 1D1 1Q2 [3 46] 1D2
 Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17 	GND 4 45 GND 1Q3 5 44 103
 Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C 	1Q4 [] 6 43 [] 1D4 V _{CC} [] 7 42 [] V _{CC}
 High-Impedance State During Power Up and Power Down 	1Q5 8 41 1D5 1Q6 9 40 1D6
 Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise 	GND 10 39 GND 1Q7 11 38 1D7 1Q8 12 37 1D8
 Flow-Through Architecture Optimizes PCB Layout 	1Q8 12 37 1D8 2Q1 13 36 2D1 2Q2 14 35 2D2
 High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL}) Package Options Include Plastic 300-mil 	GND 🛛 15 34 🖉 GND
Shrink Small-Outline (DL) and Thin Shrink	2Q3 16 33 2D3 2Q4 17 32 2D4
Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings	V_{CC} 18 31 V_{CC} 2Q5 19 30 2D5
description	2Q6 29 20 2D6 2ND 21 28 GND 2Q7 22 27 2D7

The 'ABT16374A are 16-bit edge-triggered D-type flip-flops with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

These devices can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components

OE does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16374A is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT16374A is characterized for operation from -40° C to 85° C.



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26 2D8

25

2CLK

2Q8 23

24

2<mark>0E</mark>

SCBS205C - MARCH 1993 - REVISED MAY 1997

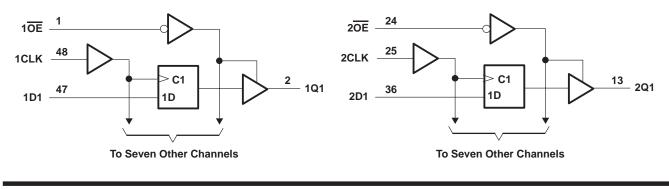
	FUNCTION TABLE (each flip-flop)										
	INPUTS		OUTPUT								
ŌE	CLK	D	Q								
L	\uparrow	Н	Н								
L	\uparrow	L	L								
L	H or L	Х	Q ₀								
Н	Х	Х	Z								

logic symbol[†]

1 <mark>0</mark> E	1	1EN			
1CLK	48	> C1			
2OE	24	2EN			
20L 2CLK	25	> C2			
ZULK			لے		
1D1	47	1D	1 🗸	2	1Q1
1D2	46			3	1Q2
1D3	44			5	1Q3
1D4	43			6	1Q4
1D5	41			8	1Q5
1D6	40			9	1Q6
1D7	38	<u> </u>		11	1Q7
1D8	37			12	1Q8
2D1	36	2D	2 ▽	13	2Q1
2D2	35		_ •	14	2Q2
2D3	33			16	2Q3
2D4	32			17	2Q4
2D4	30			19	2Q5
2D5	29			20	2Q6
2D0 2D7	27	<u> </u>		22	2Q7
2D7 2D8	26	<u> </u>		23	2Q7
200					240

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





SCBS205C - MARCH 1993 - REVISED MAY 1997

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input voltage range, V_I (see Note 1) Voltage range applied to any output in the high or power-off state, V_O Current into any output in the low state, I_O : SN54ABT16374A SN74ABT16374A Input clamp current, I_{IK} ($V_I < 0$)	0.5 V to 7 V 0.5 V to 5.5 V 96 mA 128 mA
Output clamp current, I _{OK} (V _O < 0)	
Package thermal impedance, θ_{JA} (see Note 2): DGG package	
DL package	
Storage temperature range, T _{stg}	–65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT	16374A	SN74ABT	16374A	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	4.5	5.5	V	
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	V	
ЮН	High-level output current			-24		-32	mA
IOL	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.



SCBS205C - MARCH 1993 - REVISED MAY 1997

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAD		теот с		٦	Γ _A = 25°C	2	SN54ABT	16374A	SN74ABT1	6374A	UNIT		
PAF	RAMETER	IESIC	ONDITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNIT		
VIK		V _{CC} = 4.5 V,	lj = -18 mA			-1.2		-1.2		-1.2	V		
		V _{CC} = 4.5 V,	I _{OH} = -3 mA	2.5			2.5		2.5				
Varia		V _{CC} = 5 V,	I _{OH} = –3 mA	3			3		3		v		
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				v		
		VCC = 4.5 V	I _{OH} = -32 mA	2*					2				
			I _{OL} = 48 mA			0.55		0.55			V		
VOL	$V_{CC} = 4.5 V$		I _{OL} = 64 mA			0.55*				0.55	v		
V _{hys}					100						mV		
lj		$V_{CC} = 0$ to 5.5			±1		±1		±1	μA			
IOZPU	ŧ	$V_{CC} = 0 \text{ to } 2.1$ $V_{O} = 0.5 \text{ to } 2.7$			±50		±50		±50	μΑ			
IOZPD	ŧ	$V_{CC} = 2.1 V \text{ to}$ $V_{O} = 0.5 \text{ to } 2.7$			i	±50		±50		±50	μA		
IOZH		$V_{CC} = 2.1 \text{ V} \text{ to}$ $V_{O} = 2.7 \text{ V}, \overline{\text{OE}}$				10		10		10	μA		
I _{OZL}		$V_{CC} = 2.1 \text{ V} \text{ to}$ $V_{O} = 0.5 \text{ V}, \overline{\text{OE}}$				-10		-10		-10	μΑ		
loff		V _{CC} = 0,	$V_{I} \text{ or } V_{O} \leq 4.5 \text{ V}$			±100				±100	μΑ		
ICEX	Outputs high	V _{CC} = 5.5 V,	V _O = 5.5 V			50		50		50	μΑ		
IO§		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA		
	Outputs high					2		2		2			
	Outputs low	V _{CC} = 5.5 V, I _C				72		72		72	mA		
ICC	Outputs disabled	$V_{I} = V_{CC}$ or GN	1D			2		2		2			
∆ICC¶	-	V _{CC} = 5.5 V, O Other inputs at	ne input at 3.4 V, V _{CC} or GND			1.5		1.5		1.5	mA		
Ci		VI = 2.5 V or 0.5	5 V		3.5						pF		
Co		V _O = 2.5 V or 0	.5 V		9.5						pF		

* On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at V_{CC} = 5 V.

[‡] This parameter is characterized, but not production tested.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V _{CC} = 5 V, T _A = 25°C [#]		SN54ABT16374A		SN74ABT	16374A	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency	0	150	0	150	0	150	MHz
tw	Pulse duration, CLK high or low	3.3		3.3		3.3		ns
t _{su}	Setup time, data before CLK↑	1.1		1.3		1.1		ns
th	Hold time, data after CLK [↑]	1.3		1.5		1.3		ns

[#] These values apply only to the SN74ABT16374A.



SCBS205C - MARCH 1993 - REVISED MAY 1997

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

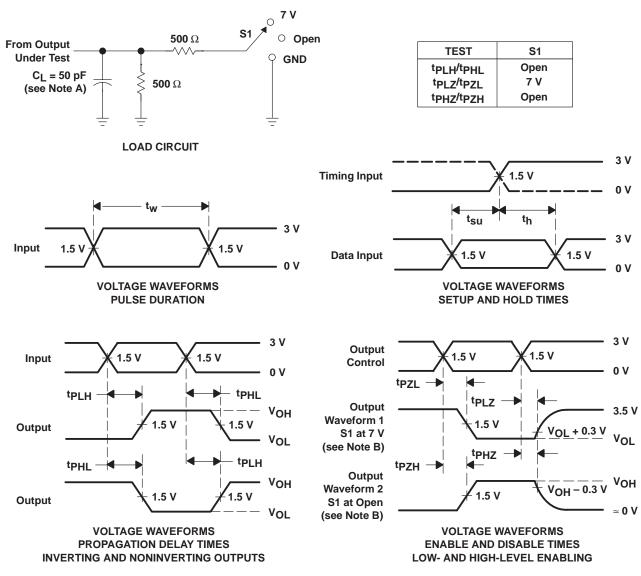
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V(Т,	CC = 5 V A = 25°C	/, ;	MIN M	МАХ	UNIT
			MIN	TYP	MAX			
fmax			150			150		MHz
tPLH	CLK	CLK Q		4.3	5.7	1.5	6.9	ns
^t PHL	OER	Q Q	2.7	4.7	6.1	2.2	6.9	113
^t PZH	OE	Q	1.2	3.4	4.8	0.8	6.1	ns
tPZL	ÛE	Q	1.6	3.5	4.9	1.2	5.5	115
^t PHZ	ŌĒ	Q	2.2	5.5	8.6	1.8	9.6	00
tPLZ	UE	Q Q	2.2	4.3	6.2	1.8	7.2	ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

				SN74	ABT163	374A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	Vo Tj	CC = 5 V A = 25°C	!, ;	MIN	МАХ	UNIT
			MIN	TYP	MAX			
fmax			150			150		MHz
tPLH	CLK	Q	1.8	4.3	5.4	1.8	6.2	ns
^t PHL	OLK	Q	2.7	4.7	5.6	2.7	5.9	113
^t PZH	ŌĒ	Q	1.2	3.4	4.8	1.2	5.6	ns
^t PZL	ÛE	Q	1.6	3.5	4.7	1.6	5.3	115
^t PHZ	OE	Q	2.2	5.5	7.1	2.2	8.2	ns
t _{PLZ}	UE	Q	2.2	4.3	5.8	2.2	6.6	115



SCBS205C - MARCH 1993 - REVISED MAY 1997

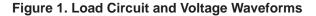


PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9320101MXA	ACTIVE	CFP	WD	48	1	TBD	A42 SNPB	N / A for Pkg Type
74ABT16374ADGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABT16374ADGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16374ADGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16374ADL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16374ADLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16374ADLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16374ADLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ABT16374AWD	ACTIVE	CFP	WD	48	1	TBD	A42 SNPB	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	-	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16374ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74ABT16374ADLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1



PACKAGE MATERIALS INFORMATION

11-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16374ADGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0
SN74ABT16374ADLR	SSOP	DL	48	1000	346.0	346.0	49.0

MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



MECHANICAL DATA

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

DL (R-PDSO-G**)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118



MECHANICAL DATA

MCFP010B - JANUARY 1995 - REVISED NOVEMBER 1997

CERAMIC DUAL FLATPACK

WD (R-GDFP-F**)

48 LEADS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only
 - E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA
 - GDFP1-F56 and JEDEC MO-146AB



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